CLAIMS

1. A composition for an encapsulant film, the composition comprising an ethylene/alpha-olefin copolymer satisfying the following conditions (a) to (d):

(a) a density is 0.85 to 0.89 g/cc;

(b) a molecular weight distribution is 1.5 to 2.3;

(c) a melting temperature is 85°C or less; and

(d) a free volume proportional constant (C_2) is 300 to 550, determined with an ARES-G2 as set out in the specification,

wherein the alpha-olefin is comprised in 10 to 50 mol% with respect to the copolymer,

wherein a melt index ($MI_{2.16}$, 190°C, 2.16 kg load conditions) of the ethylene/alpha-olefin copolymer is 3 dg/min to 10 dg/min and

wherein the alpha-olefin comprises one or more selected from the group consisting of propylene, 1-butene, 1-pentene, 4-methyl-1-pentene, 1-hexene, 1-heptene, 1-octene, 1-decene, 1-undecene, 1-dodecene, 1-tetradecene, 1-hexadecene and 1-eicosene.

2. The composition for an encapsulant film according to claim 1, wherein the molecular weight distribution of the ethylene/alpha-olefin copolymer is 1.8 to 2.2.

3. The composition for an encapsulant film according to claim 1, wherein a melt flow rate ratio (MFRR, $MI_{10}/MI_{2.16}$) which is a value of a melt index (MI_{10}, 190°C, 10 kg load conditions) with respect to a melt index ($MI_{2.16}$, 190°C, 2.16 kg load conditions) of the ethylene/alpha-olefin copolymer is 8.0 or less.

4. The composition for an encapsulant film according to claim 1, wherein a crystallization temperature of the ethylene/alpha-olefin copolymer is 70°C or less.

5. The composition for an encapsulant film according to claim 1, wherein a weight average molecular weight of the ethylene/alpha-olefin copolymer is 40,000 to 150,000 g/mol.

6. The composition for an encapsulant film according to claim 1, further comprising one or more selected from the group consisting of a crosslinking agent, a crosslinking auxiliary agent, a silane coupling agent, an unsaturated silane compound, an amino silane compound, a light stabilizer, a UV absorbent and a thermal stabilizer.

7. An encapsulant film comprising the composition for an encapsulant film according to any one of claims 1 to 6.

8. A solar cell module comprising the encapsulant film of claim 7.